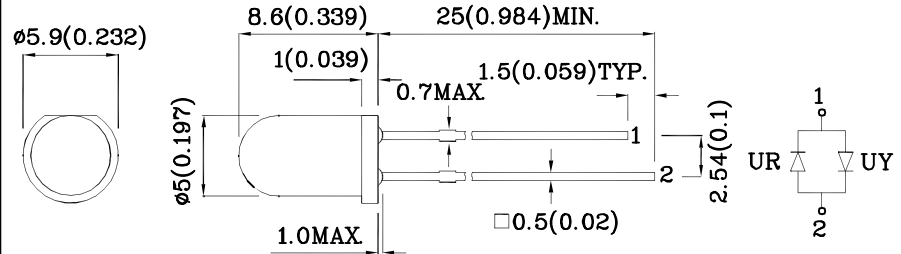


Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



Package Schematics



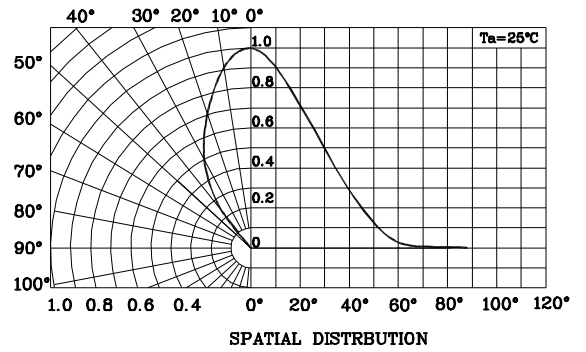
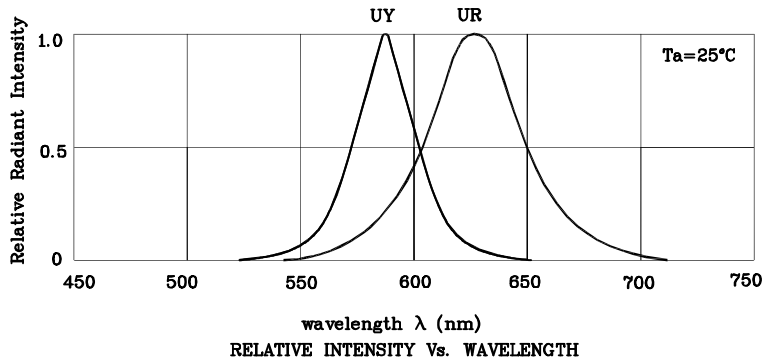
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

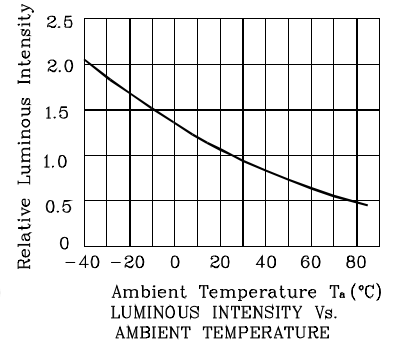
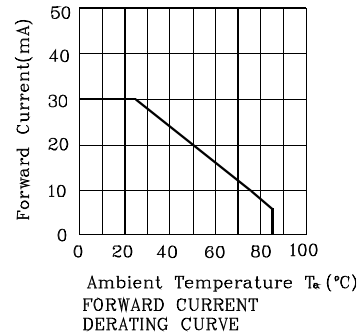
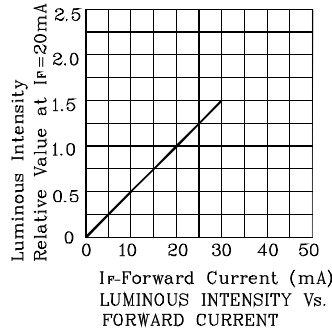
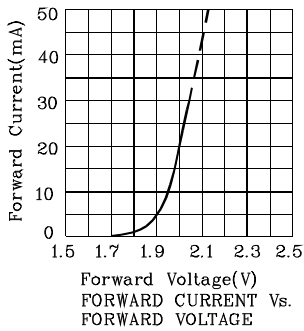
Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/ GaP)	UY (GaAsP/ GaP)	Unit
Forward Current	I _F	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	160	140	mA
Power Dissipation	P _D	75	75	mW
Operating Temperature	T _A	-40 ~ +85		°C
Storage Temperature	T _{stg}	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/ GaP)	UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2	2.1	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	2.5	V
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	627	590	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	625	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	45	35	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	20	pF

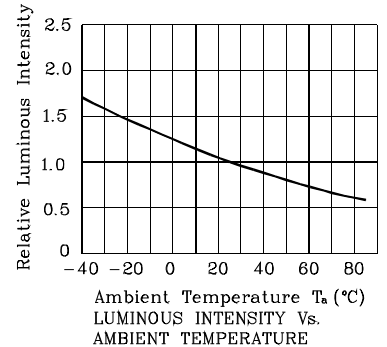
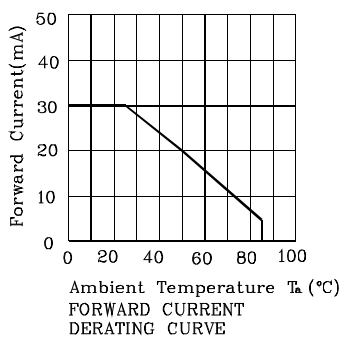
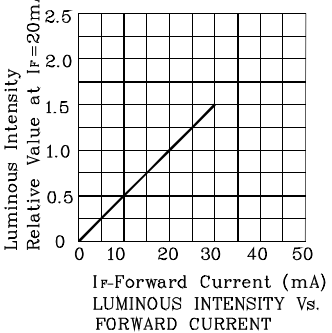
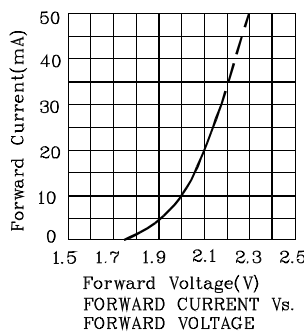
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
LUYR58M	Red	GaAsP/GaP	White Diffused	12	29	627	60 $^\circ$
	Yellow	GaAsP/GaP		4	9	590	



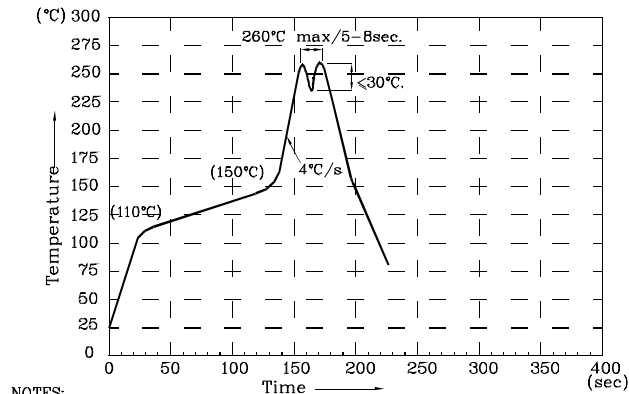
UR



UY



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature $245^\circ\text{C} \sim 260^\circ\text{C}$. The maximum soldering temperature should be less than 260°C .
2. Do not apply stress on epoxy resins when temperature is over 85°C .
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C .
5. No more than once.

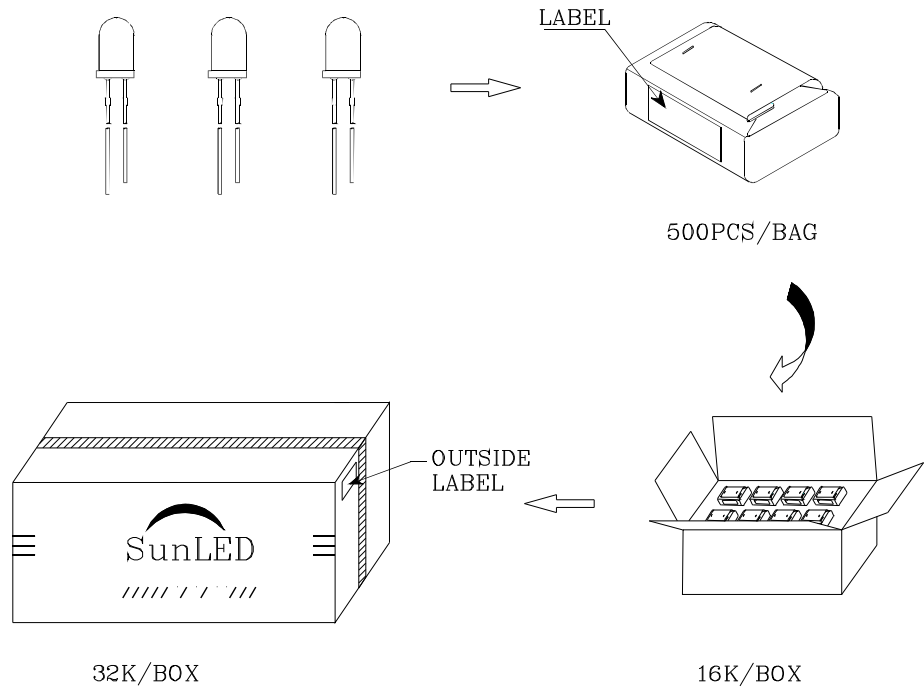
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



		Q.C. Q C XX XX XXXX PASSED
P/NO : Lxxx58x		
QTY : 500 pcs		CODE: XXX
S/N : XX		
LOT NO:  XXXXXXXXXXXXXXXXXXXXXXXX		
RoHS Compliant		